	e standard			Е	Storage				
	Operating temperature range Operating humidity range		-35 °C to +85 °C(Note1) t 40% to 80% (Note2) \$		Storage temperature range		-10 °C to +60 °C(Note3		)
Rating					Storage humidity rano	je	40% to 70%		
	Voltage		250 V AC		Applicable	connector	DF1E-∗S-2.5C		
	Current		AWG20 to 24: 3A		V	oltage	AC 30V	AC 30V	
			AWG26: 2A AWG28: 1A		UL, CSA		AWG20 to 22: 3A		
			AWG28: TA AWG30: 0.5A			Gurrent	AWG24 to 28: AWG30: 0.		
			Speci	ificatio	ons				
Item		Test method				Requirements			A
Construc	tion								
General examination		Visually and by measuring instrument.				According to drawing.			X
Marking		Confirmed visually.							>
	characteris								
Contact resistance millivolt evel method.		20 mV MAX, 1 mA(DC or 1000 Hz).			30 mΩ	30 mΩ MAX.			-
Insulation resistance		500 V DC.			1000	1000 MΩ MIN.			_
Voltage proof		650 V AC for 1 min.			No flas	No flashover or breakdown.			-
Mechani	cal charac	teristics							
Mechanical			sertions and extractions.		① Co	ntact resistan	ce: 30 mΩ MAX.		
						② No damage, crack or looseness of parts.			_
Vibration		Frequency 10 to 55 Hz, single amplitude			① No	① No electrical discontinuity of 1 μs.			
		0.75 mm, at 2 h, for 3 directions.				damage, cra	ck or looseness of parts.	Х	_
Shock		490 m/s <sup>2</sup> duration of pulse 11 ms at 3 times for 3 directions.							_
Environn	nental cha	racteristic	S						
Rapid chang		Temperatu	rre -55→ 5 to $35$ →+ $85$ → 5 to	35 °c	① Co	ntact resistan	ce: 30 mΩ MAX.	x	
emperature		Time $30 \rightarrow 5 \text{ max} \rightarrow 30 \rightarrow 5 \text{ max}$ min			0	(2) Insulation resistance: 1000 M $\Omega$ MIN.			-
Dama haat		Under 5 cycles. Exposed at 40 ± 2 °c, 90 to 95 %, 96 h.				<ul> <li>③No damage, crack or looseness of parts.</li> <li>① Contact resistance: 30 mΩ MAX.</li> <li>② Insulation resistance: 500 MΩ MIN.</li> <li>③No damage, crack or looseness of parts.</li> </ul>			
Damp heat (Steady state)					0				_
					-				
Resistance to soldering		1) Automa	1) Automatic soldering (flow)			No deformation of case of excessive			
heat		Solder te	Solder temperature, 260 °C for			ness of the ter		Х	-
		Immersion, duration, 10 sec.							
		2) Manual Solderin	soldering g iron temperature : 300 °C,						
			g time : 3 sec.						
			No strength on contact.						
			Soldered at solder temperature,			Solder shall cover a minimum of			T
Solderability	1	Soldered a						v	
-	,	Soldered a	t solder temperature, nsertion duration, 5 s.				being immersed.	Х	-
Remarks	, e the temperatur	Soldered a 235 °c for i	nsertion duration, 5 s.				being immersed.	X	
Remarks Note1: Include Note2:No con	e the temperatur densing.	Soldered a 235 °c for i e rising by curr	nsertion duration, 5 s.		95 % 0		being immersed.	X	
Remarks Note1: Include Note2:No cone Note3:Apply to	e the temperatur densing. o the condition o	Soldered a 235 °c for i e rising by curr of long term stor	nsertion duration, 5 s. ent. age for unused products before p		95 % d	of the surface	being immersed.	X	-
Remarks Note1: Include Note2:No cone Note3:Apply to After po	e the temperatur densing. o the condition o cb board,operati	Soldered a 235 °c for i e rising by curr f long term stor ng temperature	nsertion duration, 5 s. ent. age for unused products before p and humidity range is applied for	r interim stor	95 % d	of the surface			-
Remarks Note1: Include Note2:No cone Note3:Apply to After po Coun	e the temperatur densing. o the condition o cb board,operati	Soldered a 235 °c for i e rising by curr f long term stor ng temperature	nsertion duration, 5 s. ent. age for unused products before p	r interim stor	95 % d	of the surface	being immersed.		ate
Remarks Note1: Include Note2:No cone Note3:Apply to After po Coun	e the temperatur densing. o the condition o cb board,operati	Soldered a 235 °c for i e rising by curr f long term stor ng temperature	nsertion duration, 5 s. ent. age for unused products before p and humidity range is applied for	r interim stor	95 % d	of the surface			
Remarks Note1: Include Note2:No cone Note3:Apply to After po Coun	e the temperatur densing. o the condition o cb board,operati	Soldered a 235 °c for i e rising by curr f long term stor ng temperature	nsertion duration, 5 s. ent. age for unused products before p and humidity range is applied for	r interim stor	95 % d	of the surface	Checked KI. AKIYAMA	Da 15. (	06. 1
Remarks Note1: Include Note2:No cond Note3:Apply to After po Cound	e the temperatur densing. o the condition o cb board,operati	Soldered a 235 °c for i e rising by curr f long term stor ng temperature	nsertion duration, 5 s. ent. age for unused products before p and humidity range is applied for	r interim stor	95 % d	ansportation. Approved Checked	Checked KI. AKIYAMA KI. AKIYAMA	Da 15. ( 15. (	06.1 06.1
Remarks lote1: Include lote2:No conv lote3:Apply to After po Coun	e the temperatur densing. o the condition o cb board,operati It	Soldered a 235 ° <sub>C</sub> for i e rising by curre flong term stor ng temperature Descriptio	nsertion duration, 5 s. ent. rage for unused products before p and humidity range is applied for n of revisions	r interim stor	95 % d	ansportation. Approved Checked Designed	Checked KI. AKIYAMA KI. AKIYAMA TS. KUMAZAWA	Da 15. ( 15. ( 15. (	)6. )6. )6.
Remarks lote1: Include lote2:No cond After po Coun M	e the temperatur densing. o the condition o cb board,operati nt	Soldered a 235 °c for i e rising by curr f long term stor ng temperature Descriptio	nsertion duration, 5 s. ent. age for unused products before p and humidity range is applied for n of revisions	r interim stor	95 % d a. Designed	Approved Checked Designed Drawn	Checked KI. AKIYAMA KI. AKIYAMA TS. KUMAZAWA MI. SAKIMURA	Da 15. ( 15. ( 15. ( 15. (	D6. 1 D6. 1 D6. 1
Remarks Note1: Include Note2:No con- Note3:Apply to After po Coun	e the temperatur densing. o the condition o cb board,operati nt	Soldered a 235 °c for i e rising by curre of long term stor ng temperature Descriptio	nsertion duration, 5 s. ent. age for unused products before p and humidity range is applied for n of revisions	st	95 % of the second seco	Approved Checked Designed Drawn ng no.	Checked KI. AKIYAMA KI. AKIYAMA TS. KUMAZAWA MI. SAKIMURA ELC-336779-3	Di 15.0 15.0 15.0 15.0 35-00	D6. 1 D6. 1 D6. 1 D6. 1
Remarks Note1: Include Note2:No conv After po Coun	e the temperatur densing. o the condition o cb board,operati nt	Soldered a 235 °c for i e rising by curr of long term stor ng temperature Descriptio d, refer to IEC est AT:Assu Specifi	nsertion duration, 5 s. ent. age for unused products before p and humidity range is applied for n of revisions	st F	95 % d a. Designed	Approved Checked Designed Drawn ng no.	Checked KI. AKIYAMA KI. AKIYAMA TS. KUMAZAWA MI. SAKIMURA	Da 15.0 15.0 15.0 15.0 35-00 5)	06. 1 06. 1 06. 1 06. 1

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